

Product Change Notification (PCN)

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| Device affected (product name): nRF905 nRF9E5 | Device version / Build Code: B B |
| Agreement reference (number + version): N/A | PCN no.: 008 (rev 1.1) |
| | Date: 2008-02-01 |
| Customer's reference: N/A | Nordic Semiconductor reference: Supply Chain Manager |

Description of change:

- Change of production site for Assembly and Test from ASE Chung-Li, Taiwan to Amkor Technology – Philippines, Inc (ATP)
- Package singulation changed from Punch to Saw
- Change of test platform
- Build code changed from B to C

Impact: Does the change affect product:

- | | | |
|----------------------------|--|---|
| 1. Form? | <input type="checkbox"/> No | <input checked="" type="checkbox"/> Yes – describe: Please see "Consequences" section below |
| 2. Fit? | <input type="checkbox"/> No | <input checked="" type="checkbox"/> Yes – describe: Please see "Consequences" section below |
| 3. Function? | <input checked="" type="checkbox"/> No | <input type="checkbox"/> Yes – describe: _____ |
| 4. Quality or Reliability? | <input type="checkbox"/> No | <input checked="" type="checkbox"/> Yes – describe: Please see "Verification" section below |
- Classification of change Minor Major

Reason:

The change takes place as part of a consolidation on a standard package technology and site for existing QFN products.

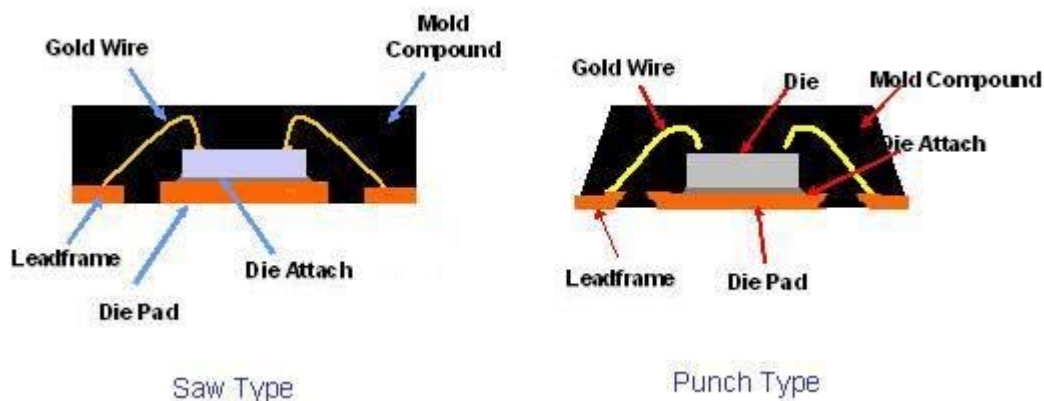
Consequences:

Function:

- No changes in functionality or parametric performance.

Form:

- The cross sections of build code B Punch type package and build code C Saw singulated packages are different.



Fit:

- The packages are designed to be interchangeable and fit the same PCB land pattern. Please note, some marginal changes to package pad dimensions should be verified. For details, see package outline tables below.

Quality and reliability

- Improved MSL performance

Verification:

Samples are available from Nordic Semiconductor.

Package outlines are compliant with Jedec MO-220.

Nordic guarantees that the reliability of the nRF905 and nRF9E5 build code C is equal to or better compared to build code B.

Build code C has been qualified for moisture sensitivity performance at MSL level 2 at 260°C per Jedec standard (build code B ships with MSL level 3).

The new test solution imposes no change to the electrical performance limits by which the product is tested. In order to ensure this, an extensive correlation program has been carried out prior to release for production.

Marking:

The products with new package will be marked with the new build code C:

| Item | Value |
|---------|------------|
| Line #1 | NRF C |
| Line #2 | 905 or 9E5 |
| Line #3 | YYWWLL |

Abbreviations:

YY – 2 digit Year number

WW – 2 digit Week number

LL – 2 letter wafer lot number code

Package dimensions

| Build code C (new package) | | | | | | | | |
|-----------------------------------|------|------|------------|------|---------|----------|-------|------|
| | A | A1 | A3 | b | D/E | e | D2/E2 | L |
| Min | 0.80 | 0.00 | | 0.18 | | | 3.2 | 0.35 |
| Typ | 0.85 | 0.02 | 0.200 REF. | 0.23 | 5.0 BSC | 0.50 BSC | 3.3 | 0.40 |
| Max | 0.90 | 0.05 | | 0.30 | | | 3.4 | 0.45 |

| Build code B (old package) | | | | | | | | |
|-----------------------------------|------|------|------------|------|---------|----------|-------|------|
| | A | A1 | A3 | b | D/E | e | D2/E2 | L |
| Min | 0.80 | 0.00 | | 0.18 | | | 3.2 | 0.30 |
| Typ | | 0.02 | 0.203 REF. | 0.23 | 5.0 BSC | 0.50 BSC | 3.3 | 0.40 |
| Max | 0.90 | 0.05 | | 0.30 | | | 3.4 | 0.50 |

Further explanation to the dimension symbols can be found in the product specification.

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| Change active from (date): February 1 st 2008 | Change active from (Build code): nRF905 Build code C nRF9E5 Build code C |
| Last order date (optional): NA | Final shipment date (optional): NA (Existing stock to be depleted) |
| Customers who require time for verification of the new version are kindly asked to inform Nordic Semiconductor through your usual sales channel. Build code C samples will be submitted upon request. Nordic Semiconductor can not guarantee available supply of build code B after May 1st 2008. | |
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| Authorization for Nordic Semiconductor | |
| Product Manager Thomas Embla Bonnerud | Date: 12.02.2008 Sign:  |
| Quality Director Ebbe Rømcke | Date: 12.02.2008 Sign:  |
| Customer acceptance | |
| Name <hr/> | Date: Sign: |
| Title <hr/> | |